User Guide LX7186A 1.4 MHz 1A Synchronous Buck Converter Evaluation Board





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1 Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

1.1 Revision **1.0**

Revision 1.0 was published in August 2017. It was the first publication of this document.



2 Product Description

The LX7186A is 1.4 MHz fixed frequency, current-mode, synchronous PWM buck (step-down) DC-to-DC converter, capable of driving a 1 A load with high efficiency, and excellent line and load regulation. The devices integrate synchronous P-channel and N-channel power MOSFET switches with low on-resistance. They accept an input voltage range from 2.5 V to 5.5 V and will enter 100% duty cycle at dropout making them ideal for powering portable equipment that runs from a single Li-ion battery.

A standard series of inductors (available from several different manufacturers) is optimized for use with the LX7186A. This feature greatly simplifies the design of switch-mode power supplies.

The converter includes standard safety features, such as over-current, short-circuit, and thermal shutdown protection. This device is available in SOT23-5L and UDFN 2x2 6L packages.

2.1 Applications

- Datacom
- Portable devices
- Smart phone

2.2 Key Features

- Input supply range: 2.5 V–5.5 V
- Output adjustable from 0.6 V–~VIN
- 100% duty cycle in dropout
- Integrated NMOS and PMOS switches
- Current mode control
- 1 A maximum output current
- Fixed 1.4 MHz frequency
- High efficiency: up to 98%
- Built-in soft-start
- Built-in OV, UV, and OT protection
- Built-in short circuit protection
- RoHS-compliant and Halogen-free
- SOT23-5L or UDFN 2x2 6L packages



3 Evaluation Board Schematic

The following illustrations show the evaluation board schematic for the LX7186A and LX7186A-UDFN device.

Figure 1 • LX7186A Evaluation Board Schematic

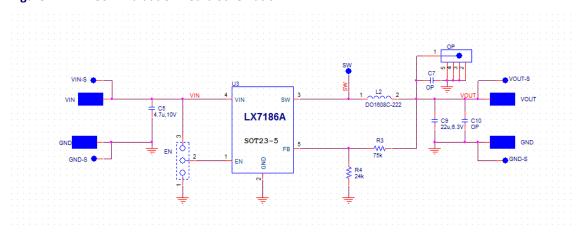
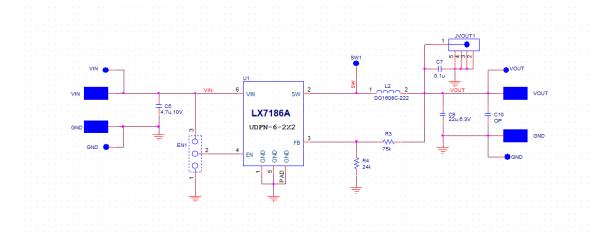


Figure 2 • LX7186A-UDFN Evaluation Board Schematic

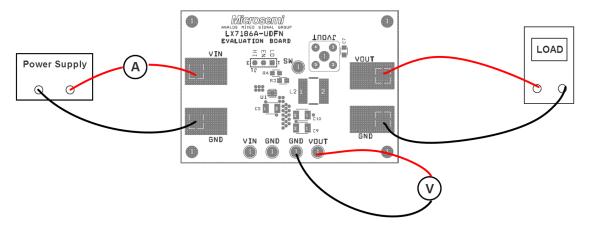




4 Basic Connection Instructions

The following illustration shows how to connect the evaluation board to the power supply.

Figure 3 • Power Supply and Load Connection





5 Recommended Operating Conditions

The following table lists the recommended operating conditions for the LX7186A evaluation board.

Table 1 • Recommended Operating Conditions

Description	Symbol	Min	Max	Unit
Input voltage	VIN	2.5	5.5	V
Output current	Іоит	0	1	Α
Operating ambient temperature	TA	-40	85	°C
Enable chip	EN	1.5		V
Shut down chip	EN		0.4	V

5.1 Setting the Output Voltage

The following equation defines the value of V_{OUT} , where V_{REF} = 0.6 V and R_4 = 24 k Ω .

$$VOUT = V_{REF} \times \left(1 + \frac{R_3}{R_4}\right)$$



6 PCB Layout of Evaluation Board

The LX7186A evaluation board is four layers. The following illustrations depict each of the board's four layers.

Figure 4 • LX7186A Top Silkscreen

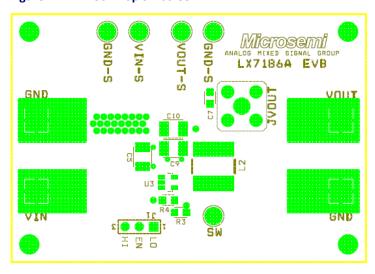


Figure 5 • LX7186A Top Layer

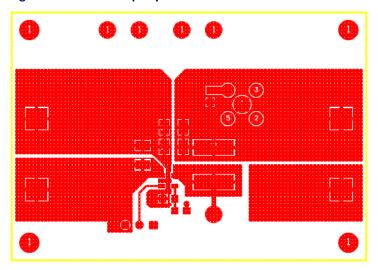




Figure 6 • LX7186A Bottom Layer

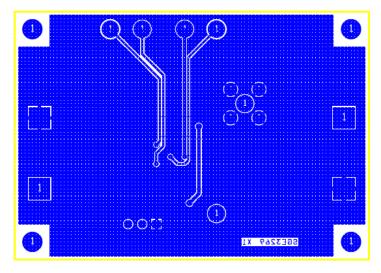


Figure 7 • LX7186A-UDFN Top Silkscreen

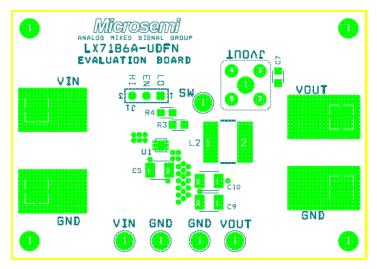




Figure 8 • LX7186A-UDFN Top Layer

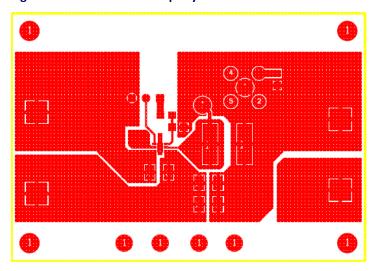
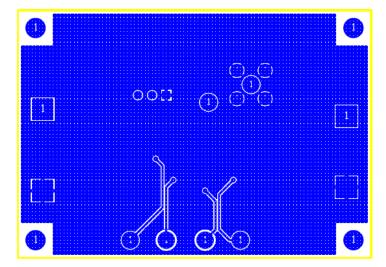


Figure 9 • LX7186A-UDFN Bottom Layer





7 Bill of Materials

The following table lists the bill of materials for the LX7186A evaluation board.

Table 2 • Bill of Materials

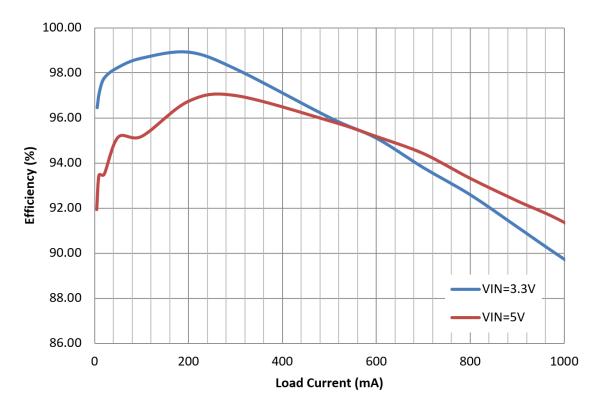
Item	Part Type	Part Description	Reference	Qty
1	Miscellaneous Components	Microsemi IC—LX7186A	U1	1
2	Miscellaneous Components	Test Point	SW, VIN, VOUT, GND, GND	5
3	Miscellaneous Components	Terminal	VIN, VOUT, GND, GND	4
4	Miscellaneous Components	Jumper/3-pin	J1	1
5	Miscellaneous Components	Scope Test Point	JVOUT	1
6	Capacitors	4.7 μF/10 V/X5R	C5	1
7	Capacitors	0.1 μF/6.3 V/X5R	C7	1
8	Capacitors	22 μF/6.3 V/X5R	C9	1
9	Resistors	75 kΩ	R3	1
10	Resistors	24 kΩ	R4	1
11	Inductor	2.2 μH/DO1813H-222 ML	L2	1



8 Efficiency Plot

The following graph shows LX7186A efficiency at a voltage output of 2.5 V.

Figure 10 • LX7186A Efficiency with 2.5 V VOUT

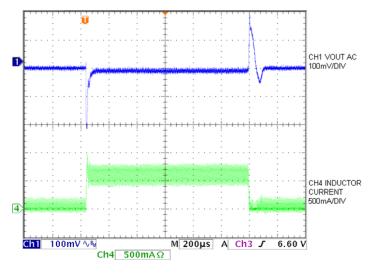




9 Dynamic Load Response

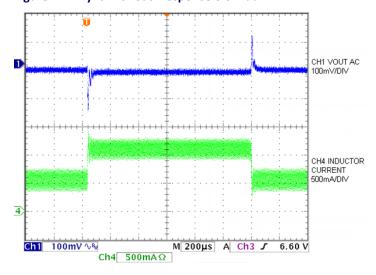
The following graphs show the dynamic load response of the LX7186A device.

Figure 11 • Dynamic Load Response with IOUT = 35 mA ↔ 600 mA



VIN = 5 V, VOUT = 3.3 V, Load 35 mA \leftrightarrow 0.6 A.

Figure 12 ● Dynamic Load Response 0.6 A ↔ 1 A



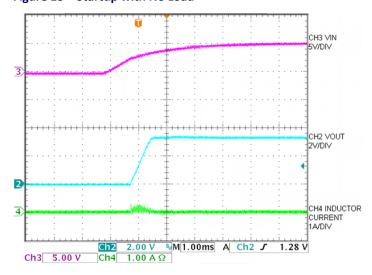
VIN = 5 V, VOUT = 3.3 V, Load 0.6 A \leftrightarrow 1 A.



10 Soft Start

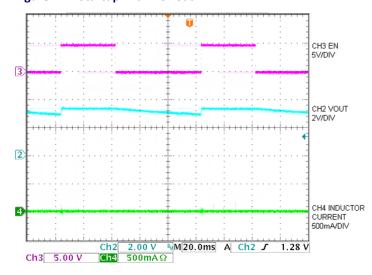
The following graphs show the soft start for the LX7186A device.

Figure 13 • Startup with No Load



VIN= 5 V, VOUT= 3.3 V, no load.

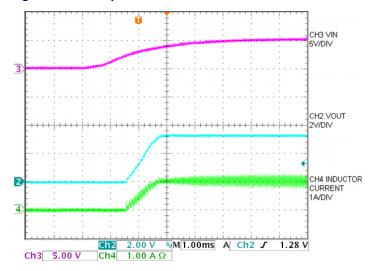
Figure 14 • Startup with No Load



VIN= 5 V, VOUT= 3.3 V, no load.

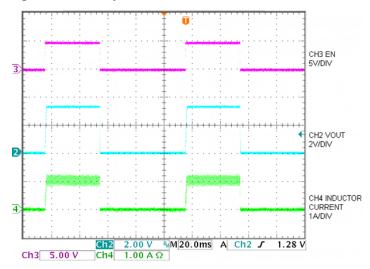


Figure 15 • Startup with 1 A Resistive Load



VIN = 5 V, VOUT = 3.3 V, 1 A load.

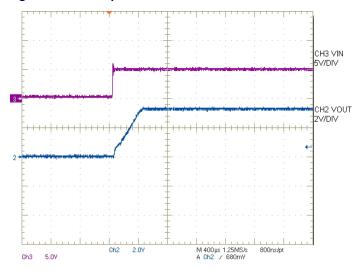
Figure 16 • Start up with 1 A Resistive Load



VIN = 5 V, VOUT = 3.3 V, 1 A load.

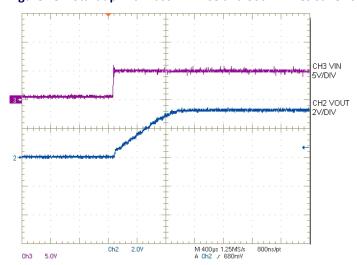


Figure 17 • Start up with Fast VIN Rise and 10 mA Resistive Load



VIN = 5 V, VOUT = 3.3 V, 10 mA load.

Figure 18 • Start up with Fast VIN Rise and 800 mA Resistive Load



VIN = 5 V, VOUT = 3.3 V, 800 mA load.



11 Ordering Information

The following table lists the ordering information for the LX7186A evaluation board.

Table 3 • Ordering Information

Part Order Number	Description
LX7186AISE	SOT23-5L
LX7186AILD	UDFN 2x2 6L
LX7186A EVALUATION BOARD	Evaluation PCB for LX7186AISE
LX7186A-UDFN EVALUATION BOARD	Evaluation PCB for LX7186AILD





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